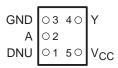
- Available in the Texas Instruments NanoStar™ and NanoFree™ Packages
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 4.6 ns at 3.3 V
- Low Power Consumption, 10-µA Max I_{CC}
- ±24-mA Output Drive at 3.3 V
- **I**off Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78. Class II
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DBV OR DCK PACKAGE (TOP VIEW) NC GND [

NC - No internal connection

YEA, YEP, YZA, OR YZP PACKAGE (BOTTOM VIEW)



DNU - Do not use

description/ordering information

This single Schmitt-trigger inverter is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC1G14 device contains one inverter and performs the Boolean function $Y = \overline{A}$. The device functions as an independent inverter, but because of Schmitt action, it may have different input threshold levels for positive-going (V_{T+}) and negative-going (V_{T-}) signals.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING‡	
	NanoStar™ – WCSP (DSBGA) 0.17-mm Small Bump – YEA NanoFree™ – WCSP (DSBGA) 0.17-mm Small Bump – YZA (Pb-free) Reel of 3000		SN74LVC1G14YEAR		
			SN74LVC1G14YZAR	CF	
	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP	Trees of 3000	SN74LVC1G14YEPR	0	
−40°C to 85°C	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)		SN74LVC1G14YZPR		
	SOT (SOT 22) DBV	Reel of 3000	SN74LVC1G14DBVR	C14	
	SOT (SOT-23) – DBV		SN74LVC1G14DBVT	C14_	
	SOT (SC-70) – DCK	Reel of 3000	SN74LVC1G14DCKR	CF	
	301 (30-10) - DON	Reel of 250	SN74LVC1G14DCKT	OF_	

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site. YEA/YZA, YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition $(1 = SnPb, \bullet = Pb-free).$



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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description/ordering information (continued)

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

FUNCTION TABLE

INPUT A	OUTPUT Y
Н	L
L	Н

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}		
Voltage range applied to any output in the high-		0.53//0.53/
(see Note 1)		–0.5 V to 6.5 V
Voltage range applied to any output in the high	•	
(see Notes 1 and 2)		–0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)		–50 mA
Output clamp current, I _{OK} (V _O < 0)		
Continuous output current, IO		
Continuous current through V _{CC} or GND		
Package thermal impedance, θ _{JA} (see Note 3):		
, , , , , , , , , , , , , , , , , , , ,	DCK package	
	YEA/YZA package	
	YEP/YZP package	
Storage temperature range, T _{stg}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The value of $V_{\mbox{CC}}$ is provided in the recommended operating conditions table.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



SN74LVC1G14 SINGLE SCHMITT-TRIGGER INVERTER

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recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
\/	Cumply voltage	Operating	1.65	5.5	V
Vcc	Supply voltage	Data retention only	1.5		V
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	VCC	V
		V _{CC} = 1.65 V		-4	
		V _{CC} = 2.3 V		-8	
IOH	OH High-level output current	V-0 - 3 V		-16	mA
		VCC = 3 V		-24	
		V _{CC} = 4.5 V		-32	
		V _{CC} = 1.65 V		4	
		V _{CC} = 2.3 V		8	
lOL	Low-level output current	V2.V		16	mA
		VCC = 3 V		24	
		V _{CC} = 4.5 V		32	
TA	Operating free-air temperature		-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS		MIN	TYP [†] MAX	UNIT	
			1.65 V	0.79	1.16		
V _{T+}			2.3 V	1.11	1.56		
Positive-going input			3 V	1.5	1.87	V	
threshold voltage			4.5 V	2.16	2.74		
			5.5 V	2.61	3.33		
			1.65 V	0.39	0.62		
V _T _			2.3 V	0.58	0.87		
Negative-going input			3 V	0.84	1.14	V	
threshold voltage			4.5 V	1.41	1.79		
			5.5 V	1.87	2.29		
			1.65 V	0.37	0.62		
ΔV_T			2.3 V	0.48	0.77		
Hysteresis			3 V	0.56	0.87	V	
$(V_{T+} - V_{T-})$			4.5 V	0.71	1.04		
		5.5 V	0.71	1.11			
	I _{OH} = -100 μA	1.65 V to 4.5 V	V _{CC} -0.1				
	I _{OH} = -4 mA						
Vari	I _{OH} = -8 mA	2.3 V	1.9		\ _\		
VOH	I _{OH} = -16 mA		3 V	2.4		V	
	I _{OH} = -24 mA]	2.3			
	I _{OH} = -32 mA		4.5 V	3.8			
	I _{OL} = 100 μA		1.65 V to 4.5 V		0.1		
	I _{OL} = 4 mA		1.65 V		0.45		
Va	I _{OL} = 8 mA		2.3 V		0.3	V	
VOL	I _{OL} = 16 mA		3 V		0.4	V	
	I _{OL} = 24 mA] 3 V		0.55		
	I _{OL} = 32 mA		4.5 V		0.55		
I _I A input	V _I = 5.5 V or GND		0 to 5.5 V		±5	μΑ	
l _{off}	V _I or V _O = 5.5 V		0		±10	μА	
lcc	$V_I = 5.5 \text{ V or GND},$	IO = 0	1.65 V to 5.5 V		10	μΑ	
ΔICC	One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND		3 V to 5.5 V	500		μΑ	
C _i	V _I = V _{CC} or GND		3.3 V		4.5	pF	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see Figure 1)

PARAMETER FROM TO (OUTPUT)	_		V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V		UNIT		
	(INPOT)	(001F01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
tpd	А	Υ	2.8	9.9	1.6	5.5	1.5	4.6	0.9	4.4	ns



SN74LVC1G14 SINGLE SCHMITT-TRIGGER INVERTER

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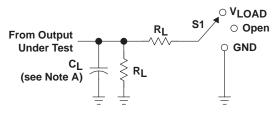
switching characteristics over recommended operating free-air temperature range, C_L = 30 pF or 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V		UNIT	
	(0011 01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
t _{pd}	A	Y	3.8	11	2	6.5	1.8	5.5	1.2	5	ns

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V	$V_{CC} = 2.5 \text{ V}$	$V_{CC} = 3.3 \text{ V}$	V _{CC} = 5 V	UNIT
		TEST CONDITIONS	TYP	TYP	TYP	TYP	UNIT
C _{pd}	Power dissipation capacitance	f = 10 MHz	20	21	22	25	pF

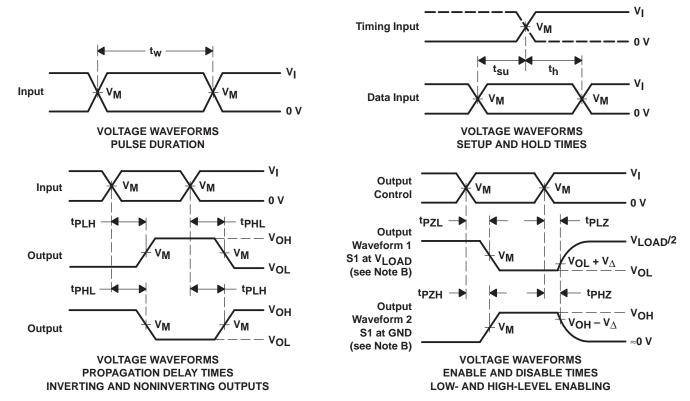
PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	VLOAD
tPHZ/tPZH	GND

LOAD CIRCUIT

	INF	PUTS	Vaa Vuonn			_	.,
VCC	٧ _I	t _r /t _f	VM	VLOAD	CL	RL	$v_{\scriptscriptstyle\Delta}$
1.8 V \pm 0.15 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	15 pF	1 M Ω	0.15 V
2.5 V \pm 0.2 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	15 pF	1 Μ Ω	0.15 V
3.3 V \pm 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	15 pF	1 Μ Ω	0.3 V
5 V ± 0.5 V	VCC	≤2.5 ns	V _{CC} /2	2×V _{CC}	15 pF	1 M Ω	0.3 V

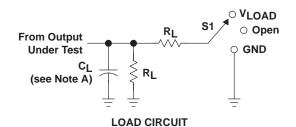


- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tplH and tpHL are the same as tpd.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

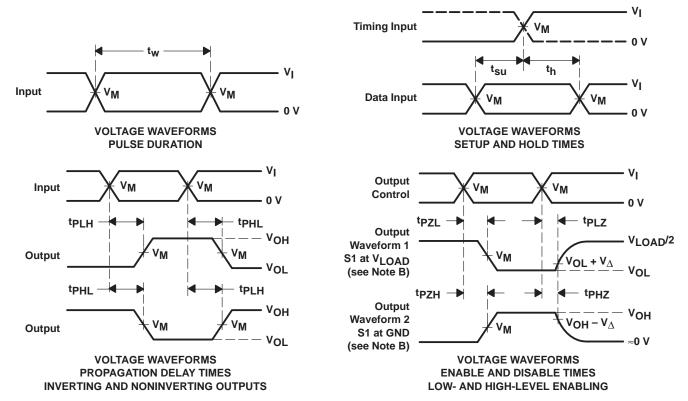


PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	V _{LOAD}
tPHZ/tPZH	GND

.,	INF	PUTS	V V			_	.,
Vcc	٧ _I	t _r /t _f	VM	VLOAD	CL	R_L	$v_{\scriptscriptstyle\Delta}$
1.8 V ± 0.15 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
3.3 V \pm 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V ± 0.5 V	VCC	≤ 2.5 ns	V _{CC} /2	2×V _{CC}	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

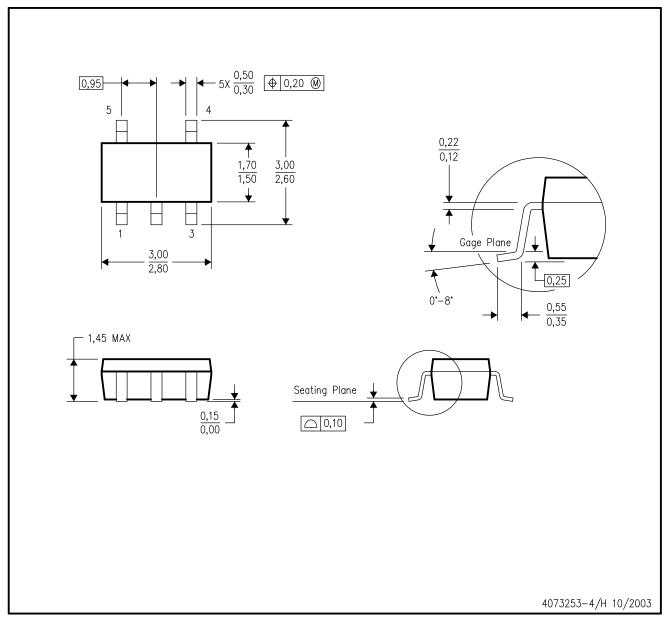
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_Ω = 50 Ω.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms



DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



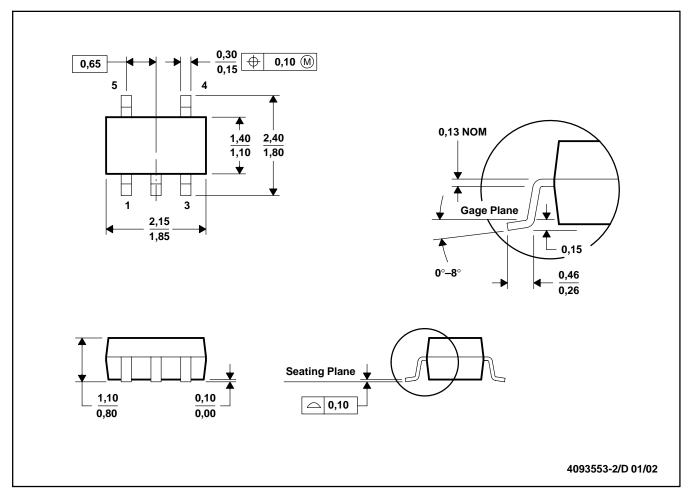
NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- C. Body dimensions do not include mold fla D. Falls within JEDEC MO—178 Variation AA. Body dimensions do not include mold flash or protrusion.



DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-203

YEA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

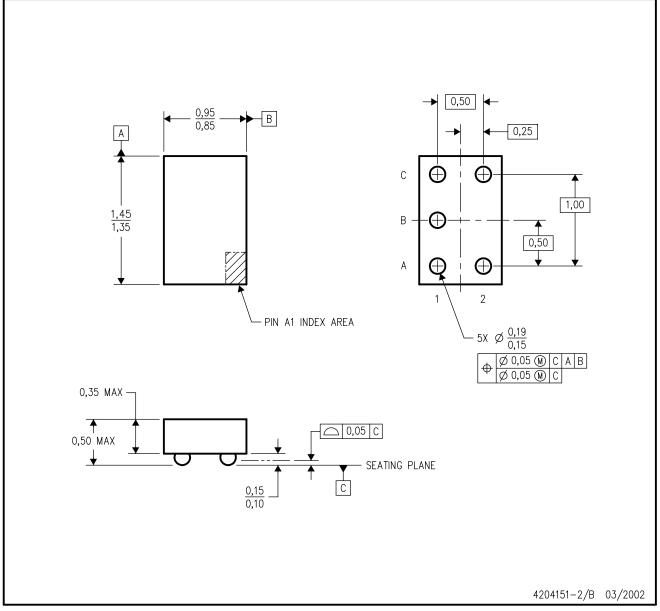
- B. This drawing is subject to change without notice.
- C. NanoStar \mathbf{M} package configuration.
- D. Package complies to JEDEC MO-211 variation EA.
- E. This package is tin-lead (SnPb). Refer to the 5 YZA package (drawing 4204151) for lead-free.

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YZA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

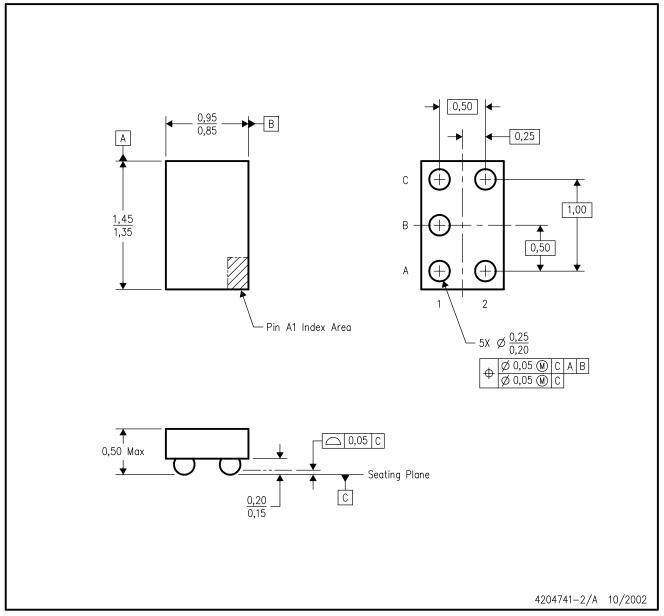
- B. This drawing is subject to change without notice.
- C. NanoFree $^{\text{TM}}$ package configuration.
- D. Package complies to JEDEC MO-211 variation EA.
- E. This package is lead-free. Refer to the 5 YEA package (drawing 4203167) for tin-lead (SnPb).

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YZP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. NanoFree™ package configuration.
- D. This package is lead-free. Refer to the 5 YEP package (drawing 4204725) for tin-lead (SnPb).

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YEP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. NanoStar \mathbf{M} package configuration.
- D. This package is tin-lead (SnPb). Refer to the 5 YZP package (drawing 4204741) for lead-free.

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